

11-12-2004

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

## 1. Name of conveying party(ies):

William H. Howland, Jr. and Brian R. Bobrzynski

## 2. Name and address of receiving party(ies)

Name: Solid State Measurements, Inc.

Internal Address:

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

## 3. Nature of conveyance:



Assignment



Merger



Security Agreement



Change of Name



Other

Street Address: 110 Technology Drive

City: Pittsburgh State: PA Zip: 15275

Execution Date: October 25, 2004

Additional name(s) & address(es) attached? ☐ Yes ☒ No

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: October 25, 2004

## A. Patent Application No.(s)

"IN-SITU WAFER AND PROBE DESORPTION  
USING CLOSED LOOP HEATING"

## B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Logsdon

Internal Address: Webb Ziesenheim Logsdon

Orkin &amp; Hanson, P.C.

Street Address: 700 Koppers Building

436 Seventh Avenue

City: Pittsburgh State: PA Zip: 15219

## 6. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41)..... \$ 40.00



Enclosed



Authorized to be charged to deposit account

## 8. Deposit account number:

23-0650

(Attach duplicate copy of this page if paying by deposit account)

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## 9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William H. Logsdon, No. 22,132

Name of Person Signing

Signature

November 5, 2004

Date

Total number of pages including cover sheet, attachments, and documents: 2

Mail documents to be recorded with required cover sheet information to: Mail Stop Assignment Recordation Services  
Director of the U.S. Patent and Trademark Office  
P.O. Box 1450, Alexandria, VA 22313-1450PATENT  
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11-5-04

ASSIGNMENT

WHEREAS, WE, William H. Howland, Jr. and Brian R. Bobrzynski, residing at:

William H. Howland, Jr.  
2535 Secretariat Drive  
Wexford, Pennsylvania 15090  
County: Allegheny  
Citizenship: USA

Brian R. Bobrzynski  
3557 Willett Road  
Pittsburgh, Pennsylvania 15227  
County: Allegheny  
Citizenship: USA

have invented certain new and useful improvements in "IN-SITU WAFER AND PROBE DESORPTION USING CLOSED LOOP HEATING" for which we have executed an application for United States Letters Patent;

AND, WHEREAS, Solid State Measurements, Inc., a corporation of the Commonwealth of Pennsylvania, having a place of business at 110 Technology Drive, Pittsburgh, Pennsylvania 15275, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner for Patents is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without expense to us, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

DATE: 10-25-04

INVENTOR: William H. Howland, Jr.  
WILLIAM H. HOWLAND, JR.

DATE: 10-25-04

INVENTOR: Brian R. Bobrzynski  
BRIAN R. BOBRZYNSKI